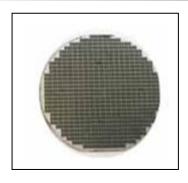
## **HOPE RF**

### **HPTA2000**

## **High Temperature Pressure Sensor**



- 0 to 2MPa pressure range
- high stability
- anti-high-temperature
- RoHS-compatible & Pb-free
- Provide the other gage pressure range sensor

#### **DESCRIPTION**

HPTA2000 is a kind of high temperature MEMS sensor based on SOI semiconductor materiel. Its operating temperature is -30~180°C. With advanced beam--diaphragm structure design and stress equipartition technology adopted, HPTA2000 sensor has the advantages of high temperature resistance, transient high temperature shock immunity, high measuring range and high overload which make it ideal for pressure self-control testing equipments used in aerospace / aviation, energy transportation, oil exploitation, heat process automation in Chemical industry, metallurgical automation, etc.

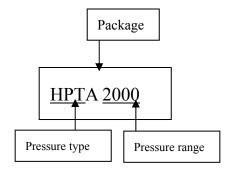
HPT series sensors have been widely used for measuring diesel spray pressure in the self-control testing components of diesel engines in vehicles and vessels. HPT sensors still can operate normally even though the environment temperature exceeds 180  $^{\circ}$ C.

HPT sensors are produced first by ion implanting the four piezoresistors into silicon. The four resistors are connected in a Wheatstone bridge arrangement, whereby two resistors increase with positive pressure while the other two decrease in resistance. When pressure is applied to the device and two ports of the resistor bridge are supplied with power source, the other two ports will output an electric signal which is directly proportional to pressure. Stress equipartition technology is introduced into the design of die, making the device more robust against high overload. Furthermore, the resistors are isolated with insulating medium which guarantees the high steadiness of sensor device.

#### Part number System

#### Package:

A: Absolute pressure sensor DIE

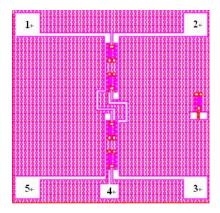


# **HOPE RF**

## Characteristics

Measurement media	Non-aggressive fluids and gases
Туре	AE2
Output signal	compensated
Pressure from	Front/ back side
Dimensions	
Chip size (mm <sup>2</sup> )	2.5×2.5
Total height (mm)	0.9
Glass thickness (mm)	0.5
Hole diameter (mm)	0.7
Maximum ratings	
Storage temperature T <sub>st</sub> (C°)	-40250
Operating temperature T <sub>a</sub> (C°)	-30180
Supply voltage (max.) V <sub>DD</sub> (V)	10
Temperature characteristics	
V <sub>DD</sub> =5V	
Temperature coefficients of the bridge	0.250.35
resistance ( %/C° )	
Temperature coefficientsof the	- 0.25 0.15
Sensitivity (%/C°)	
Temperature coefficients of the	- 0.10+0.10
Zero ( %/C°)	
Characteristics T <sub>a</sub> =25°C V <sub>DD</sub> =5V	
Bridge resistance (min/max)R <sub>s</sub>	4.0—6.0
(ΚΩ)	
Offset voltage (min/max)V <sub>0</sub>	-25+25
(MV)	
Nonlinearity (typ) $N_L$ (%FS)	±0.2
Output span $(typ)V_{SP}$ $(MV)$	2540

#### WAFER ELECTRICAL CONNECTIONS



Chip dimensions: $2.5 \times 2$	$.5 \times 0.9$ mm
---------------------------------	--------------------

Pad	Connection
1	Vout-
2	Vc
3	Vout+
4	Vd
5	Vd

#### HOPE MICROELECTRONICS CO.,LTD

4/F, Block B3, East Industrial Area, Huaqiaocheng, Shenzhen, Guangdong,

Tel: 86-755-82973805

Fax: 86-755-82973550

Email: sales@hoperf.com

Website: http://www.hoperf.com

http://www.hoperf.cn

http://hoperf.en.alibaba.com

This document may contain preliminary information and is subject to change by Hope Microelectronics without notice. Hope Microelectronics assumes no responsibility or liability for any use of the information contained herein. Nothing in this document shall operate as an express or implied license or indemnity under the intellectual property rights of Hope Microelectronics or third parties. The products described in this document are not intended for use in implantation or other direct life support applications where malfunction may result in the direct physical harm or injury to persons. NO WARRANTIES OF ANY KIND, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MECHANTABILITY OR FITNESS FOR A ARTICULAR PURPOSE, ARE OFFERED IN THIS DOCUMENT.

©2006, HOPE MICROELECTRONICS CO.,LTD. All rights reserved.